

The PostProcess™ DEMI 800™ Series leverages our proprietary patented Submersed Vortex Cavitation technology for revolutionary post-printing efficiencies; combining software, hardware, and chemistry features for optimal resin and support removal.

- AUTOMAT3D® intelligent software control of energy sources and simplified machine operation.
- Vortex pumping scheme ensures uniform chemistry exposure to finishes parts with unprecedented consistency.
- Precision control over temperature and ultrasonicgenerated cavitations for accelerated process times.
- Variable energy output to adapt to material and geometry needs results in reduced damage.

SOFTWARE FEATURES

- Variable temperature: 86-145°F / 30 63°C
- · Programmable cycle time
- Proprietary Agitation Algorithms
- · Recipe storage and recall
- · Preventative maintenance features

HARDWARE FEATURES

- · Stainless steel envelope
- Hinged envelope lid
- Process drain rack
- Magnetically driven pump
- · Multi-configuration fixture
- · Casters for easy installation

ELECTRICAL - NORTH AMERICA

DEMI 800 MODEL

120V, 20A, Connector: NEMA L5-20P

DEMI 830-120V MODEL

- 120V, 20A, Connector: NEMA L5-20P
- Dual agitation; includes heater & 1,000 W ultrasonics

DEMI 830-240V MODEL

- 240V, 20A, Connector: ABB332P6W
- Dual agitation; includes heater & 1,750 W ultrasonic

ELECTRICAL - EUROPE

DEMI 830-230V MODEL

- 230V, 20A, Connector: ABB332P6W
- Dual agitation; includes heater & 1,750 W ultrasonics

DEMI 800[™] Series (Formerly DEMI)

SUPPORT & RESIN REMOVAL



MATERIALS AND TECHNOLOGIES







FDM



Resin Removal

Support Removal

SIZE

Envelope: 18" L × 18" W × 18" H

46 cm x 46 cm x 46 cm

34.75" L x 43.5" W x 59.75" H Footprint:

88 cm x 110 cm x 152 cm

Weight: 700 lbs / 318 kg empty, 1000 lbs / 454 kg full

CONSUMABLES

40 Gallons / 151 Liters Capacity: Detergent: PLM-101-SUB for Polviet

PLM-201-SUB for FDM

PLM-403-SUB for SLA, CLIP, DLP

SAFETY FEATURES

- Emergency stop
- · Auto power down





